

Examiner's Comment/Amendment

Applicant's appeal brief, see pages 8-15, filed October 23, 2006, with respect to claims 1-6, 8-10, 12-23, 25-26, and 28-34 have been fully considered and are persuasive based on examiner's amendment, as provided below. Accordingly, the claim rejections - 35 USC § 103 of January 25, 2006 has been withdrawn. Also, the Declaration under 37 CFR 1.132 filed October 23, 2006 is sufficient to overcome the rejection of claims 1-6, 8-10, 12-23, 25-26, and 28-34 based upon Suzuki et al. (USPN 6,290,380) and Elarde (USOPN 4,532,152) references.

An examiner's amendment to the record appears below. Should the changes and/or additions be unacceptable to applicant, an amendment may be filed as provided by 37 CFR 1.312. To ensure consideration of such an amendment, it MUST be submitted no later than the payment of the issue fee.

Authorization for this examiner's amendment was given in a telephone interview with Joseph T. Helmsen on December 17, 2009.

The application has been amended as follows:

- a. Amend claim 1: "A method of manufacturing a conductive lamp housing, comprising depositing particles by direct metallization to form a layer of conductive material of 1 to 4 microns thick on a generally non-planar surface of a substrate that forms part of the lamp housing, in order to form part of one or more electrical spray circuits when said conductive material is connected to at least one or more power sources and one or more light sources."

b. Amend claim 16: "A lamp housing comprising a generally non-planar substrate, further comprising a conductive layer for one or more electrical circuits deposited directly on said substrate, wherein said conductive layer is 1 to 4 microns thick, wherein said electrical circuits are connected to at least one or more power sources and one or more light sources."

Examiner's Statement of Reasons for Allowance

The following is an examiner's statement of reasons for allowance: the claims (e.g., 1 & 16) recites a lamp housing comprising a generally non-planar substrate, further comprising a conductive layer for electrical circuits deposited directly on the substrate, wherein the conductive layer is 1 to 4 microns thick, wherein the electrical circuits are connected to at least one or more light sources and power sources.

Because none of the references disclosed the details of depositing a conductive layer directly onto the non-planar lamp-housing substrate, nor is there any motivation to further specify the conductive layer thickness being 1-4 microns, the claims are deemed patentable over the prior art of record.

Suzuki et al. (USPN 6,290,380) teaches the printed circuit board being utilized for a vehicle lamp housing and the conductive material (29) is connected to at least one or more light source(s) (37) and its power source(s) (FIGS 11-12). However, Suzuki et al. fails to include a conductive layer being deposited directly on the substrate nor its specific thickness of 1-4 microns.

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably

accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

The prior art made of record and not relied upon is considered pertinent to applicant's disclosure.

Miyashita, Takayuki (JP 08148809 A) - circuit forming method and conductor circuit forming component

Takahashi, Yoshihiro (JP 03006361 A) – method for sticking metal on polyimide film

Nakamura, Shigeo (JP 09296156 A) – thin metal layer-having interlayer adhesive film for multilayered printed wiring board, and multilayered printed wiring board using the same and its production

Murase, Heihachi (JP 03185787 A) – manufacture of printed wiring board

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Jacob Y. Choi whose telephone number is (571) 272-2367. The examiner can normally be reached on Monday-Friday (10:00-7:00).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Sandra O'Shea can be reached on (571) 272-2378. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

Jacob Y Choi
Examiner
Art Unit 2875

JC

/Jacob Y Choi/
Primary Examiner, Art Unit 2885